

### General Description

The CH15N100D combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ . This device is ideal for load switch and battery protection applications.

### Features

- Advance high cell density Trench technology
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

### Application

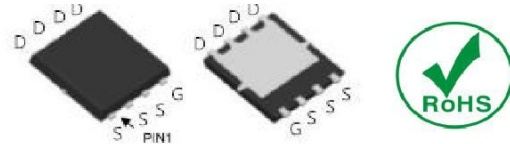
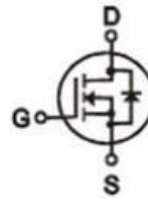
- MB/VGA Vcore
- SMPS 2<sup>nd</sup> Synchronous Rectifier
- POL application
- BLDC Motor driver

### Product Summary

$$V_{DS} = 100V$$

$$R_{DS(ON)} = 90\text{ m}\Omega$$

$$I_D = 15A$$



DFN3\*3

### Ordering Information:

Part NO.	CH15N100N
Marking	CH15N100N
Packing Information	REEL TAPE
Basic ordering unit (pcs)	5000

### Absolute Maximum Ratings ( $T_c = 25^\circ\text{C}$ )

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	20	V
Continuous Drain Current	$I_D @ TC=25^\circ\text{C}$	15	A
	$I_D @ TC=75^\circ\text{C}$	10	A
	$I_D @ TC=100^\circ\text{C}$	6.5	A
Pulsed Drain Current	$I_{DM}$	40	A
Total Power Dissipation( $TC=25^\circ\text{C}$ )	$P_D @ TC=25^\circ\text{C}$	40	W
Total Power Dissipation( $TA=100^\circ\text{C}$ )	$P_D @ TC=100^\circ\text{C}$	30	W
Operating Junction Temperature	$T_J$	-55 to 175	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 to 175	$^\circ\text{C}$
Single Pulse Avalanche Energy@ $L=0.1\text{mH}$	$E_{AS}$	100	mJ
Avalanche Current@ $L=0.1\text{mH}$	$I_{AS}$	55	A

**•Thermal resistance**

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	$R_{thJC}$	-	2.7		°C/W
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	100	°C/W
Soldering temperature, wavesoldering for 10s	$T_{sold}$	-	-	125	°C

**•Electronic Characteristics**

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	100			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	1	1.5	2.5	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS} = 100V, V_{GS} = 0V$			1.0	$\mu A$
Gate- Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 5A$		90	110	m $\Omega$
		$V_{GS} = 4.5V, I_D = 3A$		100	128	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS} = 15V, I_D = 10A$		18		S
Source-drain voltage	$V_{SD}$	$I_S = 20A$			1.20	V

**•Electronic Characteristics**

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	$C_{iss}$	$f = 1MHz$	-	811	-	pF
Output capacitance	$C_{oss}$		-	50	-	
Reverse transfer capacitance	$C_{rss}$		-	35	-	

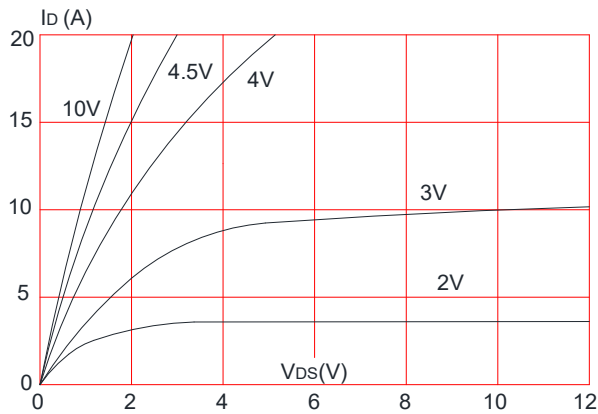
**•Gate Charge characteristics( $T_a = 25^\circ C$ )**

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	$Q_g$	$V_{DS} = 30V$	-	12	-	nC
Gate - Source charge	$Q_{gs}$	$I_D = 15A$	-	2.2	-	
Gate - Drain charge	$Q_{gd}$	$V_{GS} = 10V$	-	2.5	-	

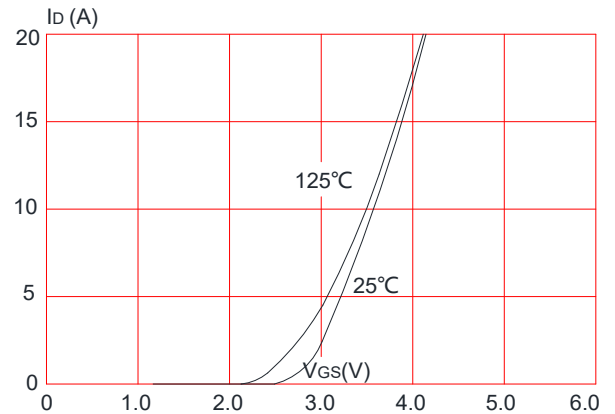
Note: ① Pulse Test : Pulse width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$  ;

## Typical Performance Characteristics

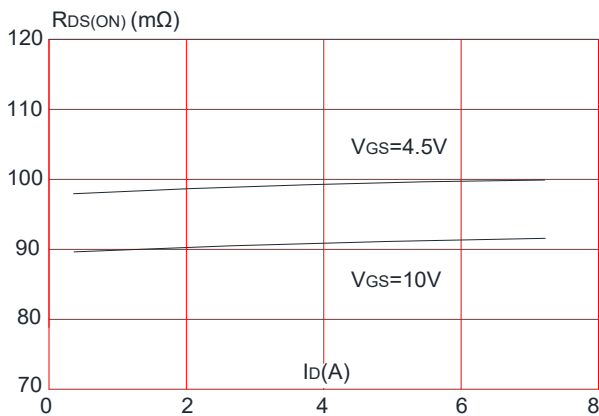
**Figure 1: Output Characteristics**



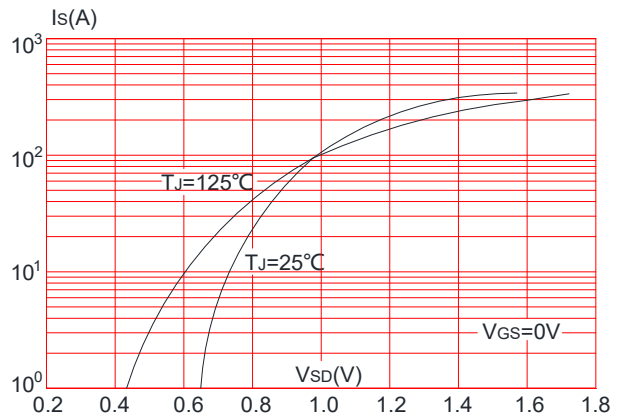
**Figure 2: Typical Transfer Characteristics**



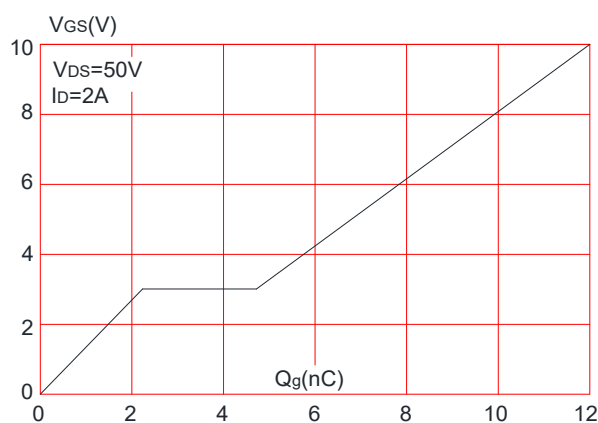
**Figure 3: On-resistance vs. Drain Current**



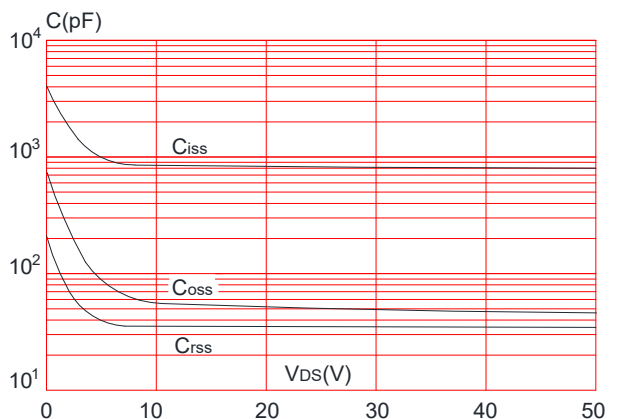
**Figure 4: Body Diode Characteristics**



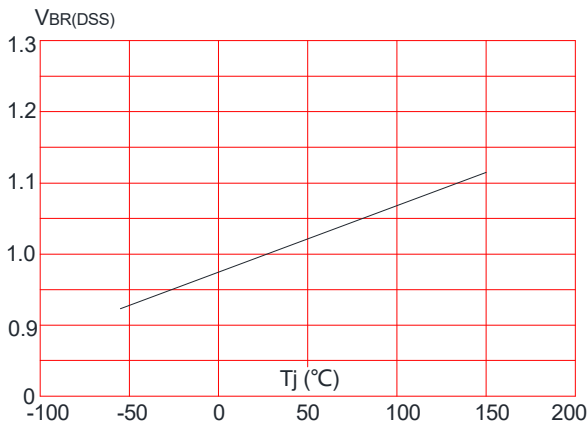
**Figure 5: Gate Charge Characteristics**



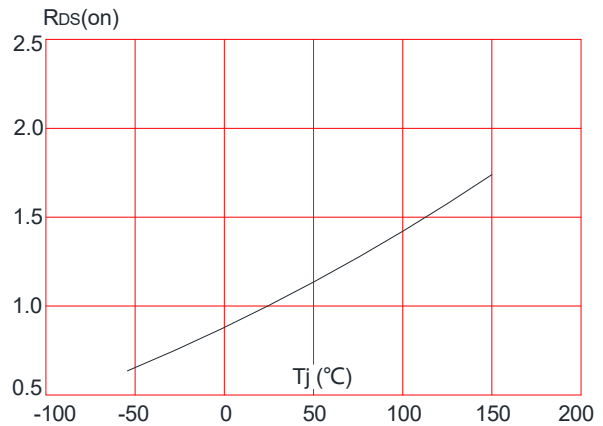
**Figure 6: Capacitance Characteristics**



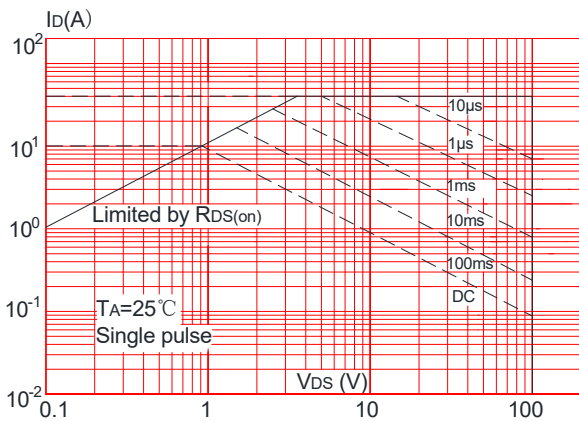
**Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**



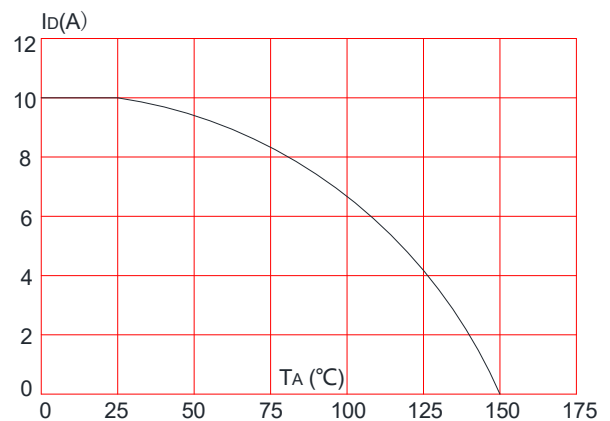
**Figure 8: Normalized on Resistance vs. Junction Temperature**



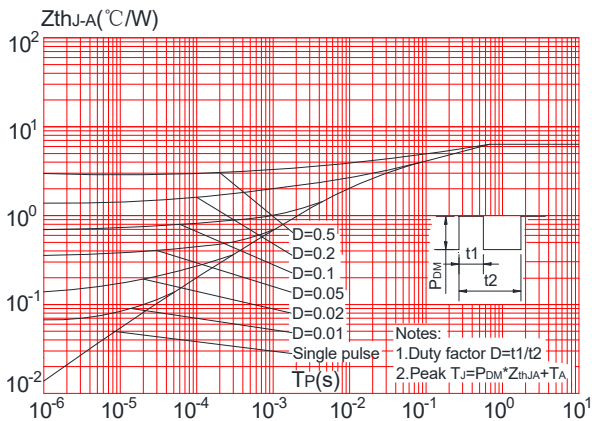
**Figure 9: Maximum Safe Operating Area**



**Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature**



**Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient**



## Test Circuit

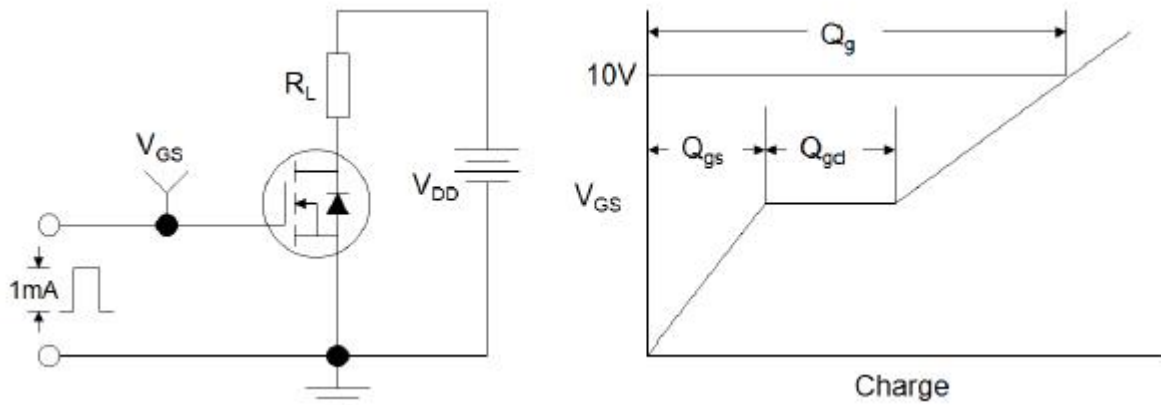


Figure1:Gate Charge Test Circuit & Waveform

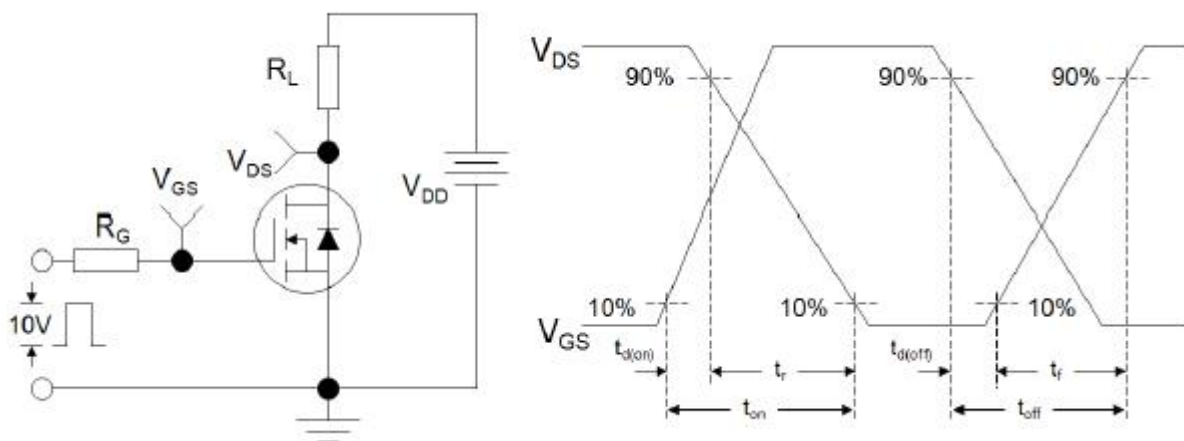


Figure 2: Resistive Switching Test Circuit & Waveforms

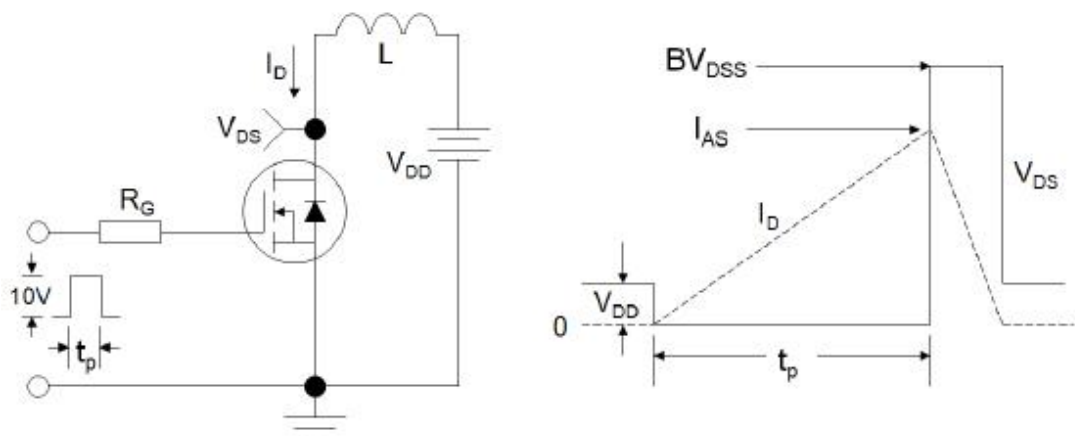
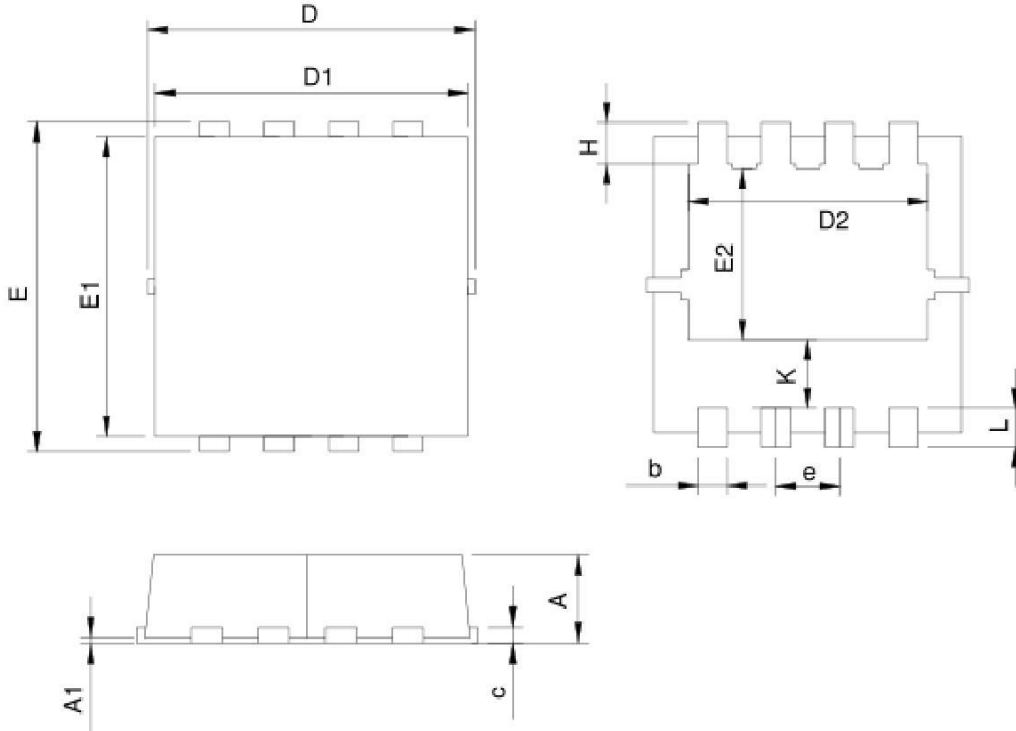


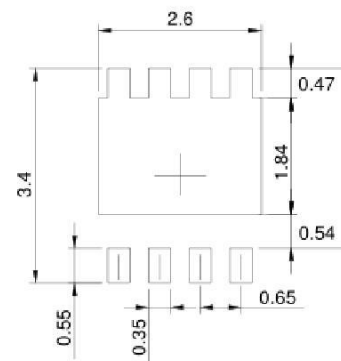
Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

**•Dimensions(DFN3×3)**

Unit: mm



SYMBOL	DFN3.3x3.3-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.70	1.00	0.028	0.039
A1	0.00	0.05	0.000	0.002
b	0.25	0.35	0.010	0.014
c	0.14	0.20	0.006	0.008
D	3.10	3.50	0.122	0.138
D1	3.05	3.25	0.120	0.128
D2	2.35	2.55	0.093	0.100
E	3.10	3.50	0.122	0.138
E1	2.90	3.10	0.114	0.122
E2	1.64	1.84	0.065	0.072
e	0.65 BSC		0.026 BSC	
H	0.32	0.52	0.013	0.020
K	0.59	0.79	0.023	0.031
L	0.25	0.55	0.010	0.022

**RECOMMENDED LAND PATTERN**


UNIT: mm